

Technical Specifications	PCB Capability
Number of layers	1-20 Layers
Max. PCB dimensions	650*520mm
Min. PCB dimensions	10*10mm
Base material	FR4 (Tg140, Tg150, Tg170)
Board thickness	0.2-5.0 mm
copper foil	0.5OZ-10OZ
Extra PTH cycles: blind – buried	yes
Min. track width /spacing	Refer to table on the right
Hole size	0.1-6.3mm
Min. finished hole size	0.15mm
min. slot width	0.8mm
min. solder mask bridge	Green-4mil, Others color- 6mil
Drilling Aspect Ratio	10:1
Drill size	0.1-6.3mm
Min. Cu to board-edge – outer layers with CNC routing	8mil
Min. Cu to board-edge – inner layers with CNC routing	10mil
Min. Cu to board-edge – outer layers with V-cutting	20mil
Min. Cu to board-edge – inner layers with V-cutting	20mil
Surface finish	ENIG, HASL , Lead-free HASL, Silver Immersion , TIN Immersion, OSP, Gold Plating; Carbon Ink, Peelable mask
Soldermask colour	Green, Black, White,red, Yellow, Blue, Matte black,matte green, purple
silkscreen legend color	White/Black/Yellow
Minimum legend width and height	White-4/24mil, Others color- 5/32mil
Outline dimension tolerance	+/-0.2MM

Copper	Min. track width /spacing
0.5 OZ	3/3 mil
1 OZ	3/4 mil
2 OZ	5/5 mil
3 OZ	7/7 mil
4 OZ	12/12 mil
5 OZ	16/16 mil
6 OZ	20/20 mil
7 OZ	24/24 mil
8 OZ	28/28 mil
9 OZ	30/30mil
10 OZ	32/30mil